LITD 05

Semiconductor And Other Electronic Components And Devices Sectional Committee

Ballots in TC 47 and TC 91 (P- Members)

TC 40

S.no	Stage	Document no.	Title	End date
1	CD	40/3174/CD	IEC 60940 ED3: Application of capacitors, resistors, inductors and complete filter units for electromagnetic interference suppression - General rules and safety requirements	2024-10-25
2	FDIS	40/3178/FDIS	IEC 62813 ED2: Lithium ion capacitors for use in electric and electronic equipment - Test methods for electrical characteristics	2024-11-15

TC 91

S.no	Stage	Document no.	Title	End date
1	CD	91/1970/CD	IEC 61760-1 ED4: Surface mounting technology – Part 1: Standard method for the specification of surface mounting components (SMDs).	2024-10-25
2	FDIS	91/1982/FDIS	IEC 61188-6-3 ED1: Circuit boards and circuit board assemblies - Design and use - Part 6-3: Land pattern design - Description of land pattern for through hole components (THT)	2024-11-01
3	FDIS	91/1983/FDIS	IEC 61189-2-809 ED1: Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-809: X/Y coefficient of thermal expansion (CTE) test for thick base materials by TMA	2024-11-01
4	CD	91/1976/CD	IEC 61249-2-54 ED1: Materials for printed boards and other interconnecting structures - Part 2-54: Reinforced base materials clad and unclad - Halogenated modified or unmodified resin system, woven E-glass laminate sheets of defined dissipation factor (less than 0,005 at 10 GHz) and flammability (vertical burning test), copper-clad for high speed applications	2024-11-08
5	CDV	91/1964/CDV	IEC 60068-2-88 ED1: ENVIRONMENTAL TESTING - Part 2-88: Tests – Test XD: Resistance of components and assemblies to liquid cleaning media	2024-11-15
6	NP	91/1980/NP	PNW 91-1980 ED1: Materials for printed boards and other interconnecting structures - Part 2-XX: Reinforced base materials clad and unclad - Non-halogenated modified or unmodified resin system, woven E-glass laminate sheets of defined dissipation factor (less than 0,005 at 10 GHz) and	2024-11-15

			flammability (vertical burning test), copper-clad for high speed applications	
7	CD	91/1981/CD	IEC 63516 ED1: Fixed folding durability test method for flexible opto-electric circuit boards	2024-11-15
8	CDV	91/1968/CDV	IEC 60068-2-83 ED2: Environmental testing - Part 2-83: Tests - Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste	2024-11-22
9	CDV	91/1973/CDV	IEC 61189-3-302 ED1: Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 3-302: Detection of plating defects in unpopulated circuit boards by computed tomography (CT)	2024-12-27
10	CDV	91/1977/CDV	IEC 61249-2-52 ED1: Materials for printed boards and other interconnecting structures - Part 2-52: Reinforced base materials clad and unclad - Thermosetting hydrocarbon resin system, woven E-glass reinforced laminate sheets of defined flammability (vertical burning test), copper-clad	2025-01-03
11	CDV	91/1978/CDV	IEC 61249-2-53 ED1: Materials for printed boards and other interconnecting structures - Part 2-53: Reinforced base materials clad and unclad - PTFE unfilled laminate sheets of defined flammability (vertical burning test), copper-clad	2025-01-03

Comments have been received for the ballot item 91/1964/CDV from M/s Vishay Components India Pvt.Ltd. Please find the comments file below. For other ballots listed above no comments have been received. For other ballots listed above, no comments have been received.

Comments
91_1964_CDV IEC 60

91_1964e_CDV.pdf

Ballots in TC 47, SC 47A, SC 47D, SC 47E, SC 47F (O- Members)

TC 47

S.no	Stage	Document no.	Title	End date
1	CD	47/2860/CD	IEC 63567-1 ED1: Semiconductor devices - Performance evaluation of semiconductor processing components and inspection equipment - Part 1: Transmittance evaluation method of EUV pellicle	2024-11-01
2	CD	47/2876/CD	IEC 63550-3 ED1: Semiconductor devices - Neuromorphic devices - Part 3: Evaluation method of spike dependent plasticity in memristor devices	2024-11-08
3	CD	47/2864/CD	IEC 63551-1 ED1: Semiconductor devices - Detection modules of autonomous land vehicle - Part 1:Testing methods of detection performance for LiDAR	2024-11-15

4	CD	47/2870/CD	IEC 63550-1 ED1: Semiconductor devices - Neuromorphic devices - Part 1: Evaluation method of basic characteristics in memristor devices	2024-11-22
5	CD	47/2871/CD	IEC 63550-2 ED1: Semiconductor devices - Neuromorphic devices - Part 2: Evaluation method of linearity in memristor devices	2024-11-22
6	CDV	47/2861/CDV	IEC 60749-7 ED3: Semiconductor devices - Mechanical and climatic test methods - Part 7: Internal moisture content measurement and the analysis of other residual gases	2024-11-29
7	CDV	47/2862/CDV	IEC 60749-21 ED3: Semiconductor devices - Mechanical and climatic test methods - Part 21: Solderability	2024-11-29
8	CDV	47/2863/CDV	IEC 60749-24 ED2: Semiconductor devices - Mechanical and climatic test methods - Part 24: Accelerated moisture resistance - Unbiased HAST	2024-11-29
9	CD	47/2874/CD	IEC 63550-4 ED1: Semiconductor devices - Neuromorphic devices - Part 4: Evaluation method of asymmetry in neuromorphic memristor devices	2024-11-29
10	CDV	47/2866/CDV	IEC 63601 ED1: Guideline for Evaluating Bias Temperature Instability of Silicon Carbide Metal-Oxide-Semiconductor Devices for Power Electronic Conversion (Fast track)	2024-12-27
11	CDV	47/2867/CDV	IEC 63602 ED1: Guidelines for Representing Switching Losses of SIC MOSFETs in Datasheets (Fast track)	2024-12-27
12	NP	47/2880/NP	PNW 47-2880 ED1: Reliability evaluation methods for vibration energy harvesters - Part 2: Temperature and humidity	2024-12-27

SC 47A

S.no	Stage	Document no.	Title	End date
1	CD	47A/1166/CD	IEC 62228-7 ED2: Integrated circuits - EMC evaluation of transceivers - Part 7: CXPI transceivers	2024-11-01
2	CD	47A/1167/CD	IEC 62132-8 ED2: Integrated circuits - Measurement of electromagnetic immunity - Part 8: Measurement of radiated immunity - IC stripline method	2024-11-22

SC 47D

S.no	Stage	Document no.	Title	End date
NIL	NIL	NIL	NIL	NIL

SC 47E

S.no	Stage	Document no.	Title	End date
1	CDV	47E/837/CDV	IEC 60747-2 ED4: Semiconductor devices - Part 2: Discrete devices - Rectifier diodes	2024-11-08
2	CDV	47E/838/CDV	IEC 60747-6 ED4: Semiconductor devices - Part 6: Discrete devices - Thyristors	2024-11-08
3	AC	47E/843/AC	Call for nominations for the Chair of SC 47E: Discrete semiconductor devices	2024-11-29

SC 47F

S.no	Stage	Document no.	Title	End date
1	CDV	47F/475/CDV	IEC 62047-50 ED1: Semiconductor devices - Micro-electromechanical devices - Part 50: MEMS capacitive microphone	2024-11-08
2	CD	47F/482/CD	IEC 62047-53 ED1: Semiconductor devices - Micro-electromechanical devices - Part 53: MEMS electrothermal transfer device	2024-11-08
3	CD	47F/483/CD	IEC 62047-52 ED1: Semiconductor Devices - Micro-electromechanical Devices - Part 52: Biaxial tensile testing method for stretchable MEMS	2024-11-08
4	CDV	47F/478/CDV	IEC 62047-49 ED1: Semiconductor devices - Micro-electromechanical devices - Part 49: Temperature and humidity test methods for piezoelectric MEMS cantilevers	2024-11-22